

Report NO.: MG00001000194

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJS8804
Package Type :	TSSOP8

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.1034%
Lead Frame	Copper	7440-50-8	92.46%	52.7503%
	Iron	7439-89-6	2.50%	
	Lead	7439-92-1	0.01%	
	Phosphorus	7723-14-0	0.02%	
	Zinc	7440-66-6	0.02%	
	Silver	7440-22-4	5.00%	
	Silver	7440-22-4	79.442%	
Die Attach	Acrylic resin	Trade secret	8.28%	3.7731%
	Acrylate	Trade secret	3.14%	
	Polybutadiene derivative	Trade secret	4.17%	
	Epoxy resin	Trade secret	2.21%	
	Butadiene copolymer	Trade secret	0.71%	
	Additive	Trade secret	1.14%	
	Peroxide	Trade secret	0.91%	
	copper	7440-50-8	99.99%	
Wire	others	/	0.01%	3.6303%
	Epoxy Resin1	Trade secret	4.00%	
Mold Compound	Epoxy Resin2	Trade secret	3.00%	37.7007%
	Phenolic Resin	Trade secret	5.00%	
	Organophosphorus compounds	Trade secret	0.54%	
	Carbon Black	1333-86-4	0.22%	
	Amorphous silica 1	60676-86-0	82.00%	
	Amorphous silica 2	7631-86-9	5.00%	
Plating	Tin	7440-31-5	100.00%	1.0421%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.